

Marker	Hits	Search Text	DB	Time stamp
1	0	cho-jin-won.in.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 11:31
2	0	xue hongxi.in.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 11:33
3	0	substrate and heat adj sink element plate plus spread\$4 with bump with emitters and metallizat\$4	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 11:35
4	119	substrate and heat adj sink element plate plus spread\$4 and emitters and metallizat\$4	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 13:40
5	0	"5549130" .PN.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 15:16
6	0	"5549440" .PN.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 17:47
7	4	"5549130" and "5549440" .PN.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 17:47
8	0	"5549130"	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:24
9	0	"5549130"	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:29
10	21	substrate and heat adj sink element plate plus spread\$4 and bump and transist	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:39
11	0	substrate and heat adj sink element plate plus spread\$4 with bump with emitter	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:44
12	0	heat adj sink element plate plus spread\$4 with bump with emitter	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:47
13	0	heat adj sink element plate plus spread\$4 with emitter	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:47

3	257/678,704,706-707.coils. and heat adj sink element plate plug spread04 with emitter and bump ball	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
4	"4004000" & "5400000" .PN.	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
15	chip die 10 with emitter and bump ball and heat adj; sink element plate plug spread04	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
16	257/710,730-738 chip die 10 with emitter and bump ball and heat adj; sink element plate plug spread04	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
2	257/710,730-738.coils. and chip die 10 with emitter and bump ball and heat adj; sink element plate plug spread04	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
3	257/710,730-738.coils. and flip adj; chip with emitter and heat adj; sink element plate plug spread04	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
3	257/678,704,706-707.coils. and flip adj; chip with emitter and heat adj; sink element plate plug spread04	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04
17	flip adj; chip with emitter and heat adj; sink element plate plug spread04	USPAT; US-PGPUB; EPC; JPC; DEPVENT; IBM_TDR	2000/07/16 19:04